Electronic companies of all types and sizes require failure analysis (FA) services. Our goal is to supply a resource of FA service providers for your reference files. The directory lists independent providers and their contact information, expertise, and types of technical services offered.

**FRAUNHOFER CAM**
Prof. Dr. Matthias Petzold
Walter-Huelse-Str. 1
06120 Halle (Saale), Germany
Tel: +49 345 5589-130
e-mail: Matthias.petzold@iwmh.fraunhofer.de
Web: www.cam.fraunhofer.de
**Services:** Diagnostics of semiconductor technologies, nanomaterials and nanoanalytics, microsystems characterization, electronic systems integration assessments, etc.
**Tools/Techniques:** Nondestructive defect localization, target sample-preparation techniques, FIB techniques and electron microscopy, surface and trace analyses, AFM, XPS, AES, TOF-SIMS, ICP-MS, crystallography and optical spectrometry, XRD, EBSD, FTIR, micro-Raman spectroscopy, surface topography and deformation, polymer characterization, DSC, DMA, TGA, TMA, corrosion testing, etc.

**FUJITSU QUALITY LABORATORY, LTD.**
4-1-1, Kamikodanaka, Nakahara-ku
Kawasaki-shi, Kanagawa
211-8588, Japan
e-mail: fql-analysis@cs.jp.fujitsu.com
Web: fujitsu.com/jp/group/fql/en/
**Services:** FA, component reliability evaluation, consulting for research and development support, preventative measures, supplier audit, materials analysis, reliability and environmental tests, educational support, software development, process improvement, supplier management, quality consulting, etc.
**Tools/Techniques:** Test equipment; measurement/microsection techniques; pressure cooker, gas, weathering, moisture resistance, temperature cycle, thermal shock, solderability, vibration, migration (insulation), and damp heat biased tests; HAST; emission microscope; whisker evaluation; SEM-EDX; SAM; plastic package decapsulation; etc.

**MATERIALS ANALYSIS TECHNOLOGY INC.**
Jubei Lab, Tai-Yuan Science Park, Failure Analysis
1F, No. 26-2, Tai-Yuan St.
Jubei City, Hsinchu County
Taiwan 302 R.O.C.
Tel: 886 3 6116678

**NANOLAB TECHNOLOGIES INC.**
1708 McCarthy Blvd.
Milpitas, CA 95035
Tel: 408.433.3320
e-mail: sales@nanolab1.com
Web: nanolabtechnologies.com
**Services:** Microscopy and imaging, materials characterization (chemical and physical), EFA, PFA, PCB analysis, FA bundled services (Level I, II Plus), FIB circuit edit, IC deprocessing, sample preparation, consulting, managed/partner labs, etc.
**Tools/Techniques:** 2-D/3-D x-ray imaging/tomography, C-SAM, chemical/laser decapsulation, argon ion and diamond milling, dimpling, wet/dry chemical IC
deprocessing, parallel mechanical polishing, FIB/SEM cross sectioning/imaging, OM, LCM, TEM, UHR-SEM, analytical TEM, EELS, EDS, STEM, SIMS, ESCA/XPS, EMMI, FMI, LSM-near IR, SOM (backside), TDR, FIB circuit edit (back/topside) with Ga/plasma beam, AFM, AES, FTIR, GC-MS, ICP-MS, Raman spectroscopy, XRD, XRR, WD-XRF, etc.

**PRIORITY LABS**
1001 S. Sherman St.
Richardson, TX 75081
Tel: 972.499.4756
e-mail: info@prioritylabs.com
Web: prioritylabs.com

**Services:** IC FA, materials analysis, counterfeit detection, etc.

**Tools/Techniques:** Deprocessing, decapsulation, TDR, electrical characterization, dye and pry, cross sectioning, SAM, optical inspection, x-ray, global isolation, SEM, FIB, etc.

**SAGE ANALYTICAL LAB, LLC**
Moe Homayounieh
6370 Nancy Ridge Dr., Suite 112
San Diego, CA 92121
Tel: 858.255.8587 or 949.338.2876
e-mail: Moe@sagefalab.com
Web: sagefalab.com

**Services:** PCB/package integrity evaluation and FA, IC circuit edit, FIB nanofabrication, electronic component

**SCIENTIA SILICON LTD.**
Bank House
81 St. Jude’s Rd.
Englefield Green
Surrey, TW20 0DF, U.K.
Tel: +44 (0) 7717 841 115
e-mail: enquiries@scientiasilicon.co.uk
Web: scientiasilicon.co.uk

**Services:** Client-focused solutions for physical FA, constructional analyses, counterfeit device investigation, expert witness and consultation, semiconductor forensic recovery and repackaging

**Tools/Techniques:** Precision mechanical polishing/grinding (front and backside, cross section), SEM/EDX, FIB, CT, light microscopy, wire bonding

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**NOTEWORTHY NEWS**

**ITC 2016**

The International Test Conference (ITC) will be held **November 15 to 17, 2016**, at the Fort Worth Convention Center in Fort Worth, Texas. ITC is the world’s premier conference dedicated to the electronic test of devices, boards, and systems and covers the complete cycle from design verification and validation, test, diagnosis, failure analysis, and back to process, yield, reliability, and design improvement. At ITC, test and design professionals can confront the challenges the industry faces and learn how these challenges are being addressed by the combined efforts of academia, design tool and equipment suppliers, designers, and test engineers.

ITC, the cornerstone of TestWeek events, offers a wide variety of technical activities targeted at test and design theoreticians and practitioners, including formal paper sessions, tutorials, panel sessions, case studies, a lecture series, commercial exhibits and presentations, and a host of ancillary professional meetings.

ITC is sponsored by the IEEE. For more information, visit itctestweek.org.